

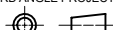


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- Diagram illustrating the structure of the top tape (TOP TAPE) with dimensions and sections:
- 引き出し方向 / PULL OUT DIRECTION**: Indicated by an arrow pointing left.
 - 100MIN.**: Dimension for the TOP TAPE BONDED PART (EMPTY).
 - トップテープ接着部 (空エンボス) / TOP TAPE BONDED PART. (EMPTY)**: The section where the top tape is bonded.
 - 部品挿入部 / COMPONENT SUPPLIER**: The section where the component is inserted.
 - 末端部 (空部) / TAIL PART (EMPTY)**: The tail part of the tape.
 - 160MIN.**: Dimension for the TAIL PART (EMPTY).
 - 400MIN.**: Total dimension for the component insertion section and the tail part.

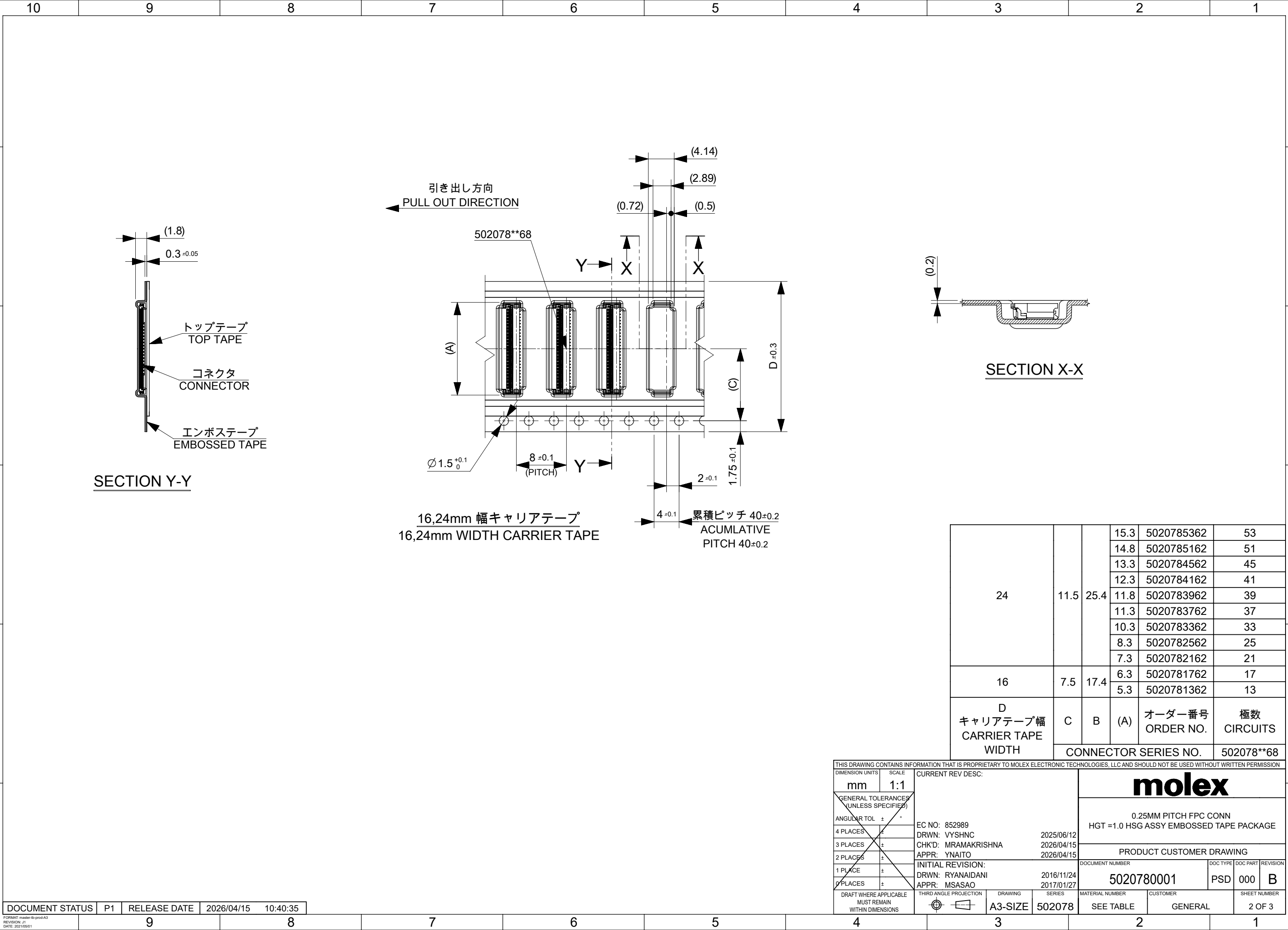
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DETAIL C

CONNECTOR SERIES NO.	502078**68
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THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION												
DIMENSION UNITS		SCALE		mm 1:1 GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± ° 4 PLACES ± 3 PLACES ± 2 PLACES ± 1 PLACE ± 0 PLACES ±								
CURRENT REV DESC:												
EC NO: 852989 DRWN: VYSHNC 25/06/12 CHK'D: MRAMAKRISHNA 26/04/15 APPR: YNAITO 26/04/15												
INITIAL REVISION: DRWN: RYANAIDANI 26/11/24 APPR: MSASAO 27/01/27												
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION 		DRAWING A3-SIZE		SERIES 502078		DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
								5020780001		PSD	000	B
								SHEET NUMBER		1 OF 3		

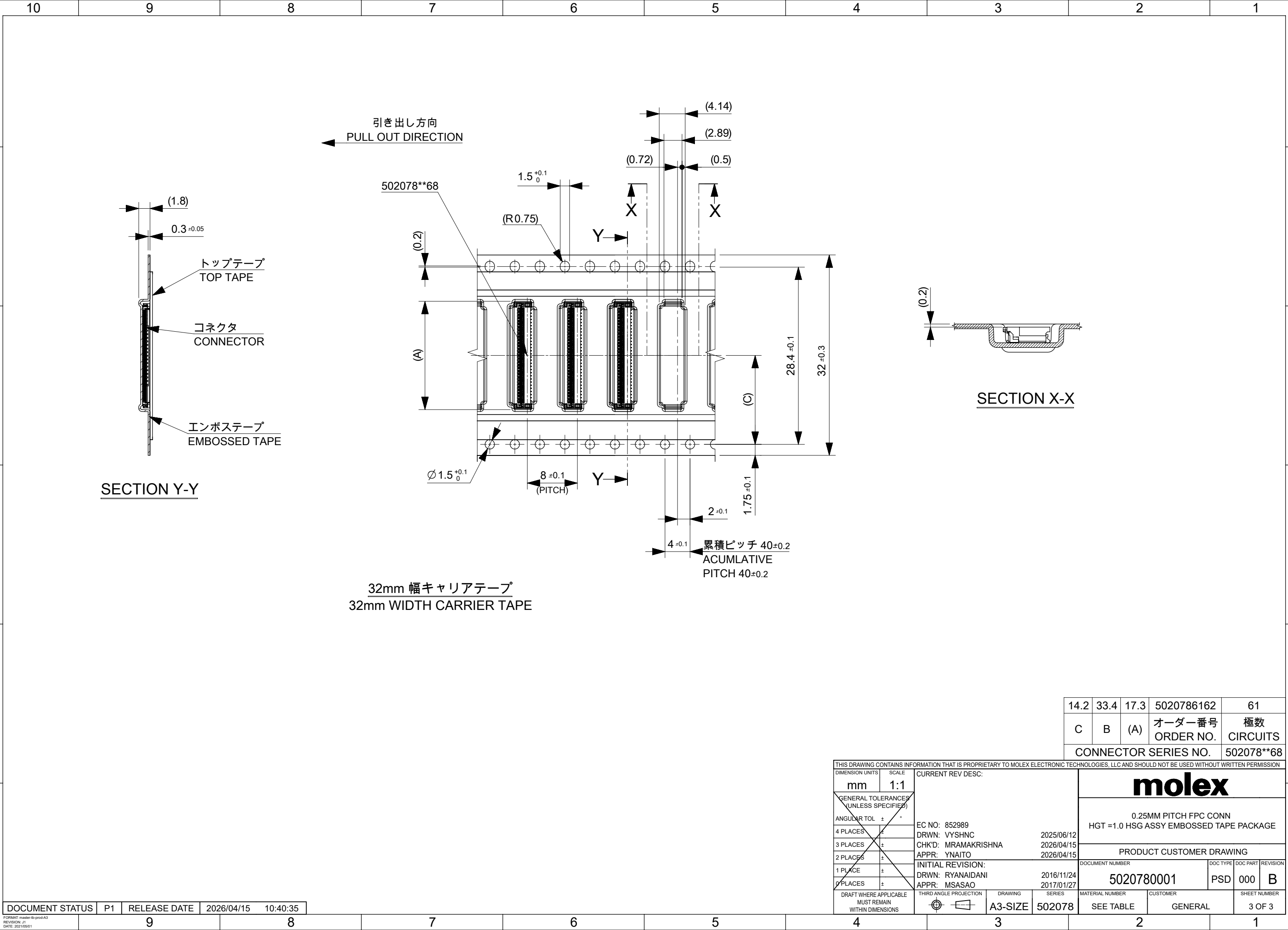
DOCUMENT STATUS	P1	RELEASE DATE	2026/04/15	10:40:35
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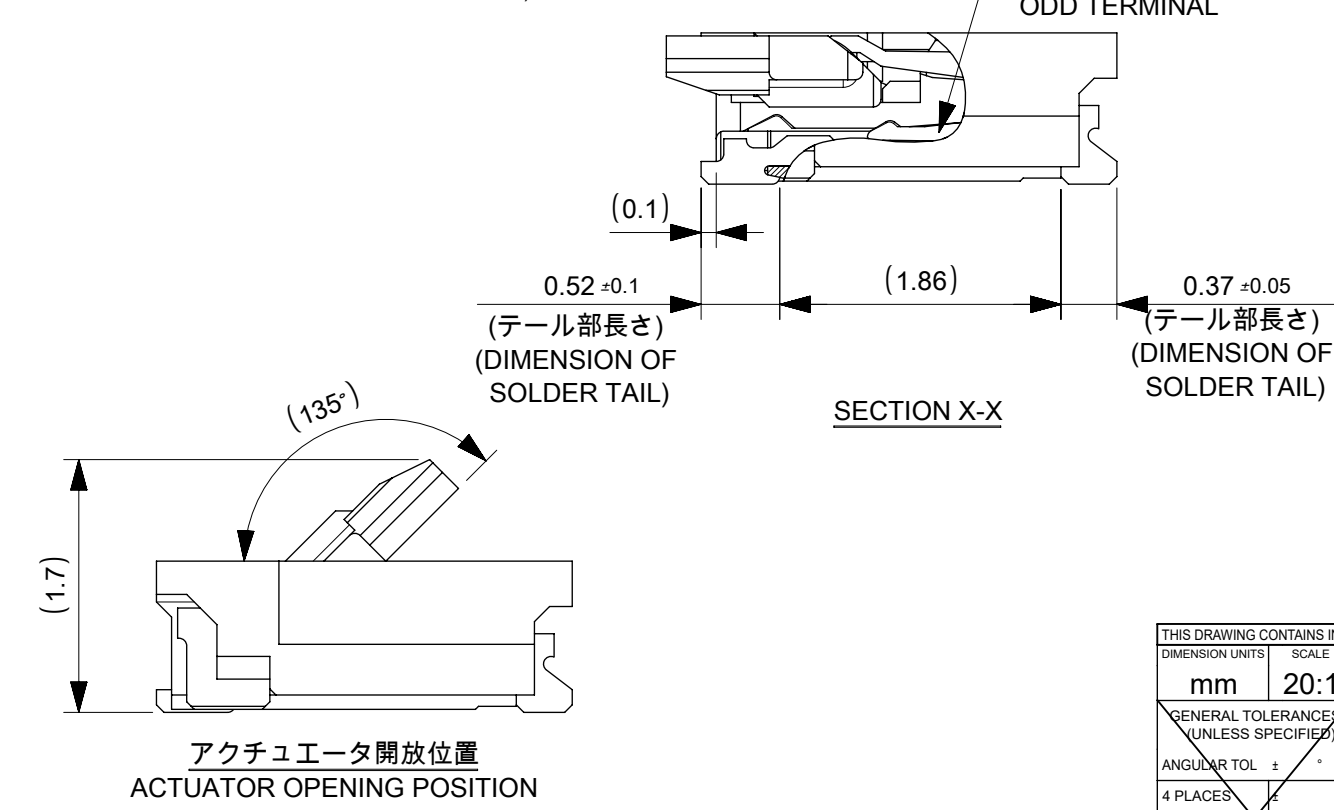
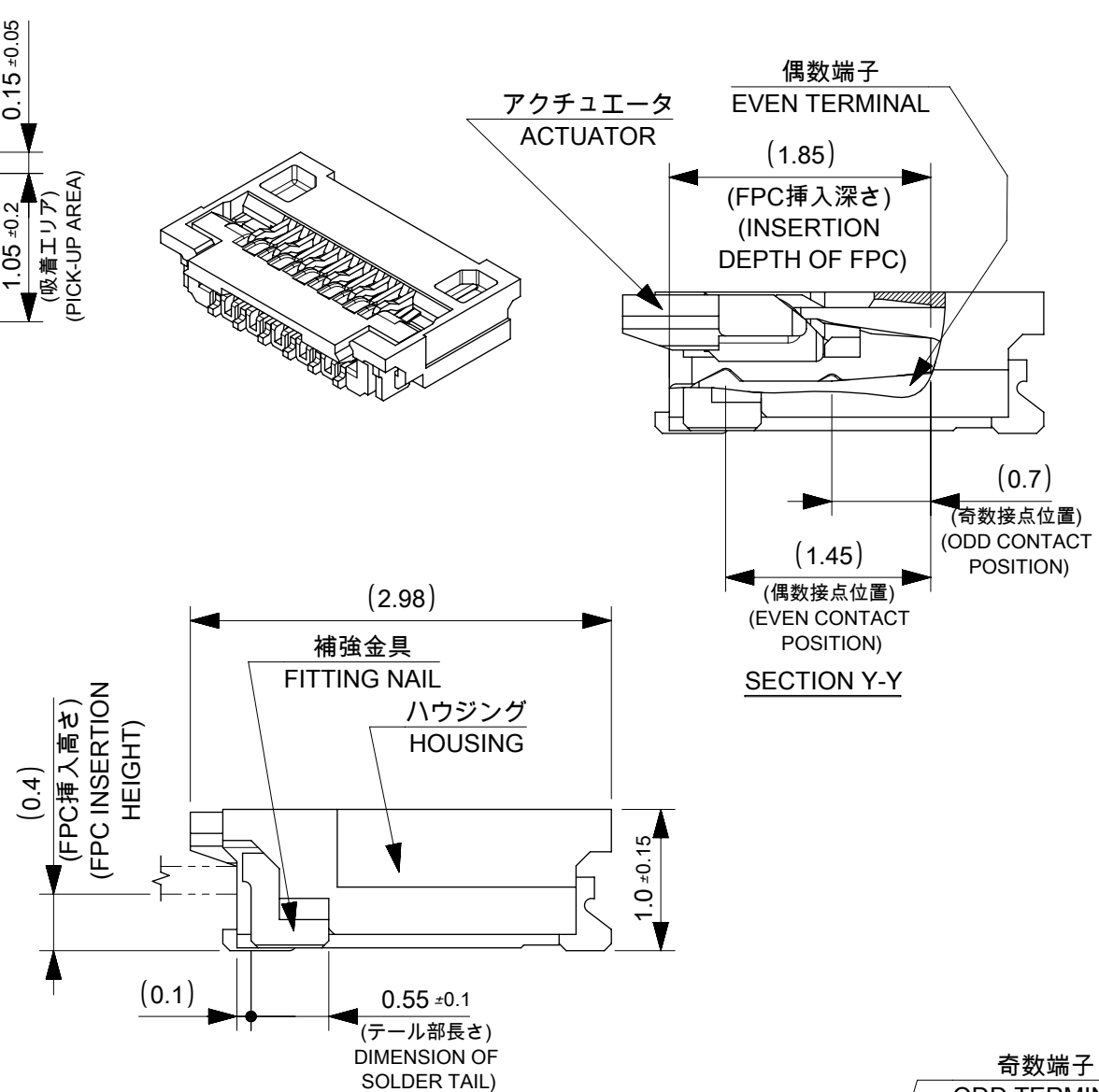
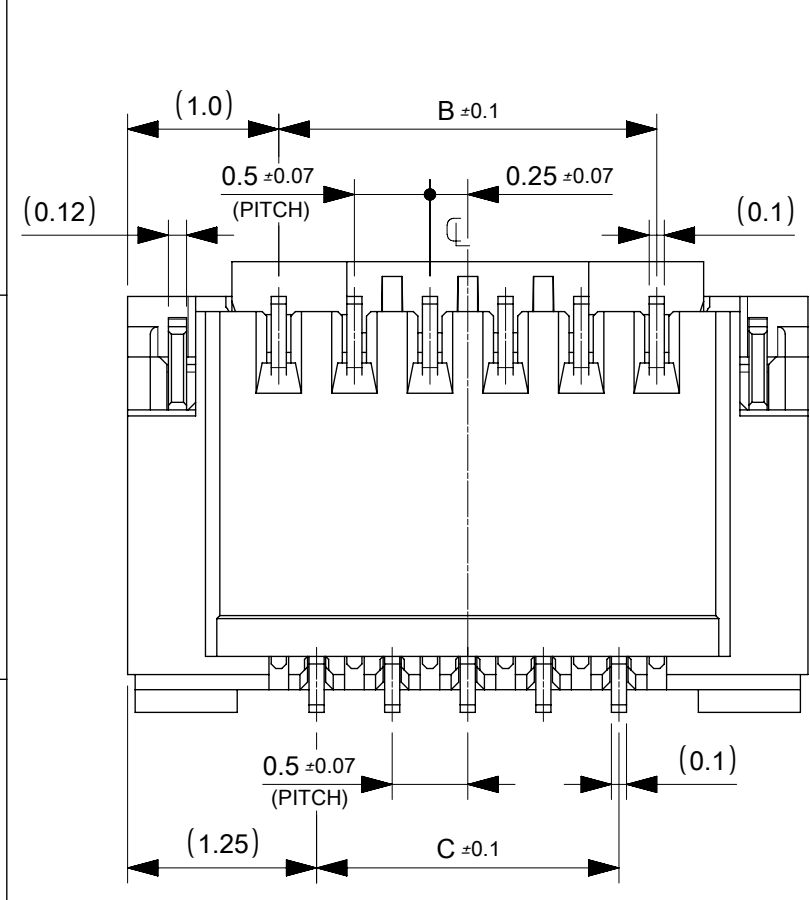
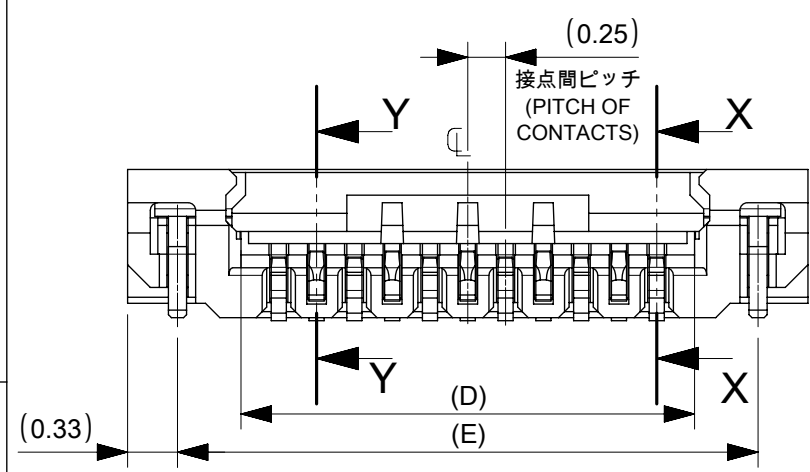
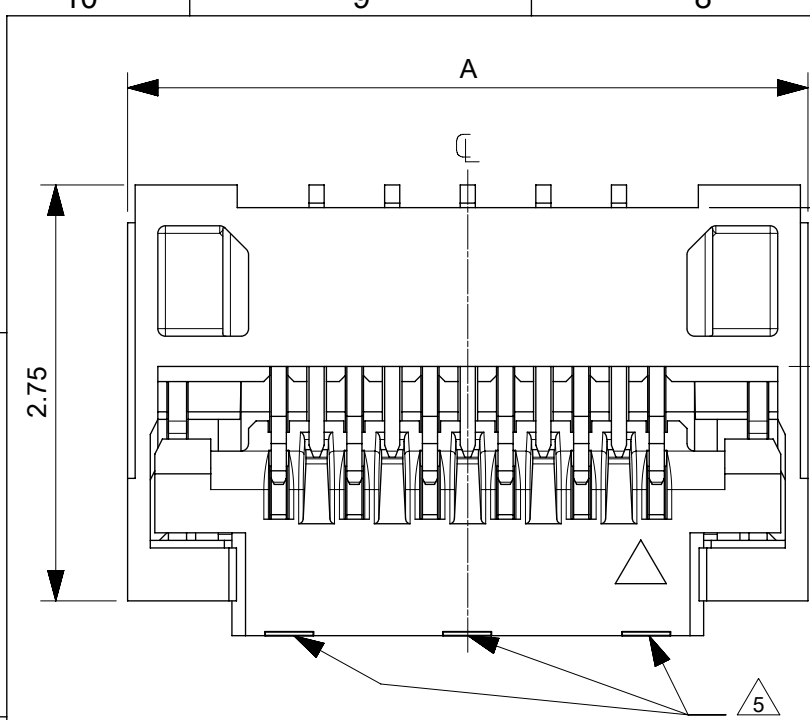


24	11.5	25.4	15.3	5020785362	53
			14.8	5020785162	51
			13.3	5020784562	45
			12.3	5020784162	41
			11.8	5020783962	39
			11.3	5020783762	37
			10.3	5020783362	33
			8.3	5020782562	25
16	7.5	17.4	7.3	5020782162	21
			6.3	5020781762	17
			5.3	5020781362	13
D キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	オーダー番号 ORDER NO.	極数 CIRCUITS
	CONNECTOR SERIES NO.				502078**68

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DIMENSION UNITS		SCALE		CURRENT REV DESC:	
mm		1:1		mo lex 0.25MM PITCH FPC CONN HGT =1.0 HSG ASSY EMBOSSED TAPE PACKAGE PRODUCT CUSTOMER DRAWING	
GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 852989		DOCUMENT NUMBER	
ANGULAR TOL		DRWN: VYSHNC		5020780001	
4 PLACES		CHK'D: MRAMAKRISHNA		PSD	
3 PLACES		APPR: YNAITO		000	
2 PLACES		INITIAL REVISION:		B	
1 PLACE		DRWN: RYANAIDANI		SHEET NUMBER	
0 PLACES		APPR: MSASAO		2 OF 3	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER
			A3-SIZE	502078	SEE TABLE
					GENERAL

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注記 NOTES

1. 使用材料 MATERIALS
ハウジング : 液晶ポリマー(UL94V-0 、ベージュ)
アクチュエータ : ポリアミド(UL94HB 、黒色)
端子 : リン青銅
補強金具 : リン青銅
HOUSING : LCP (BEIGE)
ACTUATOR : PA (BLACK)
TERMINAL : PHOSPHOR BRONZE
FITTING NAIL : PHOSPHOR BRONZE

2. メッキ仕様 PLATING
端子 TERMINAL
接点部 : 金メッキ0.1 μm以上
テール部 : 金メッキ
下地 : ニッケルメッキ1.0 μm以上
CONTACT AREA : Gold PLATING 0.1μm MINIMUM
TAIL AREA : Gold PLATING
UNDER PLATING : Nickel PLATING 1.0μm MINIMUM
金具 FITTING NAIL
表面 : スズメッキ 1.0 μm以上
下地 : ニッケルメッキ1.0 μm以上
ALL OVER : Tin PLATING 1.0μm MINIMUM
UNDER PLATING : Nickel PLATING 1.0μm MINIMUM

3. 端子、補強金具のコプラナリティーは0.1以下とする
COPLANALITY OF SOLDER TAILS AND FITTING NAILS : 0.1MAX.

4. 一般公差 : ± 0.3
GENERAL TOLERANCES: ±0.3

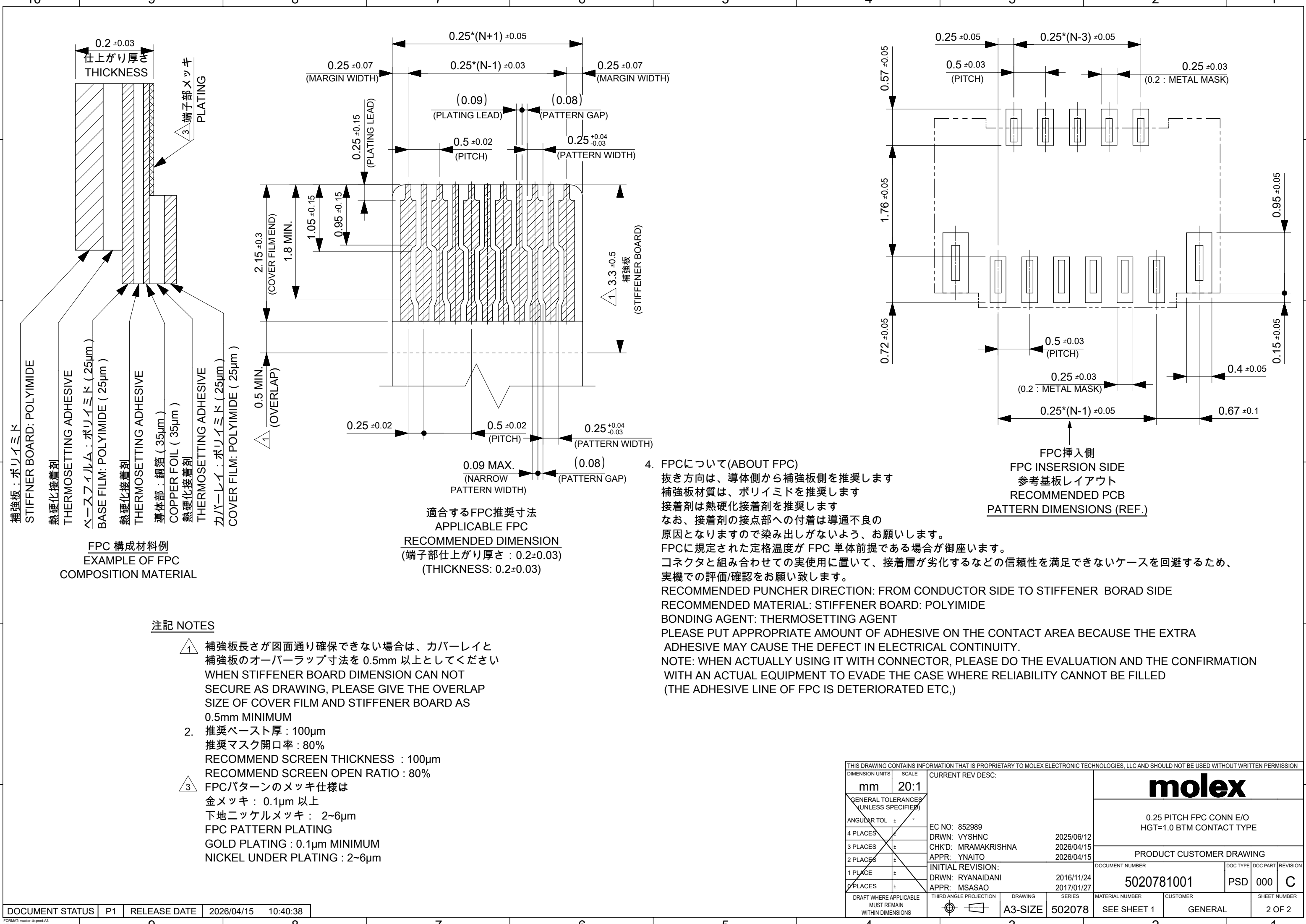
5. アクチュエータの図示箇所にゲート逃げの凹みがつきます
(極数により、レイアウトが異なります)
THERE ARE DENT SHAPES AT ACTUATOR FOR MOLDING GATE
(LAYOUT DIFFER ACCORDING TO CIRCUIT NUMBER)

6. 塩素系・臭素系難燃剤非使用
CHLORINATED AND BROMINATED FLAME RETARDANTS FREE

16.34	15.5	14.5	15	17	5020786162	5020786168	61
14.34	13.5	12.5	13	15	5020785362	5020785368	53
13.84	13	12	12.5	14.5	5020785162	5020785168	51
12.34	11.5	10.5	11	13	5020784562	5020784568	45
11.34	10.5	9.5	10	12	5020784162	5020784168	41
10.84	10	9	9.5	11.5	5020783962	5020783968	39
10.34	9.5	8.5	9	11	5020783762	5020783768	37
9.34	8.5	7.5	8	10	5020783362	5020783368	33
7.34	6.5	5.5	6	8	5020782562	5020782568	25
6.34	5.5	4.5	5	7	5020782162	5020782168	21
5.34	4.5	3.5	4	6	5020781762	5020781768	17
4.34	3.5	2.5	3	5	5020781362	5020781368	13
E	D	C	B	A	ORDER No.	MATERIAL No.	CIRCUIT =N

CONNECTOR SERIES No. 502078**68

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DIMENSION UNITS mm		SCALE 20:1	
CURRENT REV DESC:			
molex			
0.25 PITCH FPC CONN E/O HGT=1.0 BTM CONTACT TYPE			
PRODUCT CUSTOMER DRAWING			
EC NO: 852989 DRWN: VYSHNC CHK'D: MRAMAKRISHNA APPR: YNAITO		2025/06/12 2026/04/15 2026/04/15	
INITIAL REVISION: DRWN: RYANADANI APPR: MSASAO		2016/11/24 2017/01/27	
DOCUMENT NUMBER 5020781001		DOC TYPE PSD	
CUSTOMER GENERAL		SHEET NUMBER 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION DRAWING A3-SIZE	
SERIES 502078		MATERIAL NUMBER SEE TABLE	



補強板：ポリイミド
STIFFENER BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム：ポリイミド (25μm)
BASE FILM: POLYIMIDE (25μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部：銅箔 (35μm)
COPPER FOIL (35μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ：ポリイミド (25μm)
COVER FILM: POLYIMIDE (25μm)

FPC 構成材料例
EXAMPLE OF FPC
COMPOSITION MATERIAL

注記 NOTES

- 1. 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を 0.5mm 以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM
- 2. 推奨ペースト厚：100μm
推奨マスク開口率：80%
RECOMMEND SCREEN THICKNESS：100μm
RECOMMEND SCREEN OPEN RATIO：80%
- 3. FPCパターンのメッキ仕様は
金メッキ：0.1μm 以上
下地ニッケルメッキ：2~6μm
FPC PATTERN PLATING
GOLD PLATING：0.1μm MINIMUM
NICKEL UNDER PLATING：2~6μm

適合するFPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(端子部仕上がり厚さ：0.2±0.03)
(THICKNESS: 0.2±0.03)

4. FPCについて(ABOUT FPC)
抜き方向は、導体側から補強板側を推奨します
補強板材質は、ポリイミドを推奨します
接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので染み出しがないよう、お願いします。
FPCに規定された定格温度が FPC 単体前提である場合が御座います。
コネクタと組み合わせての実使用に置いて、接着層が劣化するなどの信頼性を満足できないケースを回避するため、実機での評価/確認をお願い致します。
RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BORAD SIDE
RECOMMENDED MATERIAL: STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.
NOTE: WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FPC IS DETERIORATED ETC,)

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DIMENSION UNITS		SCALE	CURRENT REV DESC:				molex 0.25 PITCH FPC CONN E/O HGT=1.0 BTM CONTACT TYPE					
mm		20:1	EC NO: 852989 DRWN: VYSHNC 2025/06/12 CHK'D: MRAMAKRISHNA 2026/04/15 APPR: YNAITO 2026/04/15 INITIAL REVISION: DRWN: RYANAIDANI 2016/11/24 APPR: MSASAO 2017/01/27									
GENERAL TOLERANCES (UNLESS SPECIFIED)												
ANGULAR TOL ± °								PRODUCT CUSTOMER DRAWING				
4 PLACES ±								DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
3 PLACES ±								5020781001		PSD	000	C
2 PLACES ±												
1 PLACE ±												
0 PLACES ±												
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIRD ANGLE PROJECTION		DRAWING	SERIES	MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
					A3-SIZE	502078	SEE SHEET 1		GENERAL		2 OF 2	

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